Amendments to the Claims:

Claims 1-15 have been amended herein. Please note that all claims currently pending and under consideration in the referenced application are shown below. Please enter these claims as amended. This listing of claims will replace all prior versions and listings of claims in the application.

Listing of Claims:

1. (Currently Amended) A semiconductor die assembly comprising: a semiconductor substrate having a first surface and a second surface, said the semiconductor substrate including at least one opening extending therethrough between saidthe semiconductor substrate first surface and said the semiconductor substrate second surface; at least one semiconductor die having an active surface with at least one electrical connection area disposed on saidthe semiconductor die active surface, saidthe at least one semiconductor die oriented having saidthe at least one electrical connection area substantially aligned with saidthe at least one semiconductor substrate opening; and at least one piece of adhesive tape interposed between and attaching said the semiconductor die active surface and saidthe semiconductor substrate first surface, a width of the one piece of adhesive tape extending at least one of to at least said edge of said at least one semiconductor substrate opening to provide a detectable surface within said at least one semiconductor substrate opening and at least to said edge of said at least one semiconductor die to provide a detectable adhesive tape surface on said semiconductor substrate first surface a width of the at least one piece of adhesive tape extending beyond at least one of an edge of the at least one semiconductor substrate opening and an edge of the at least one semiconductor die to provide a detectable surface of the at least one piece of adhesive tape.

- 2. (Currently Amended) A semiconductor die assembly comprising:
- a semiconductor substrate having a first surface and a second surface, wherein saidthe semiconductor substrate includes at least one opening defined therethrough between saidthe semiconductor substrate first surface and saidthe semiconductor substrate second surface;
- at least one semiconductor die having an active surface with at least one electrical connection area disposed on saidthe semiconductor die active surface, saidthe at least one semiconductor die oriented having saidthe at least one electrical connection area substantially aligned with saidthe at least one semiconductor substrate opening, saidthe electrical connection area disposed on saidthe semiconductor die active surface, saidthe at least one electrical connection area directly connected to at least one output electrical connection of saidthe semiconductor device; and
- at least one adhesive tape interposed between and attaching saidthe semiconductor die active surface and saidthe semiconductor substrate first surface, a width of saidthe at least one adhesive tape extending at least proximate an edge of saidthe at least one semiconductor die to an edge of saidthe at least one semiconductor substrate opening, saidthe width of saidthe at least one adhesive tape extends beyond saidthe edge of saidthe at least one semiconductor substrate opening a distance into saidthe at least one semiconductor substrate opening to provide a detectable surface within saidthe at least one semiconductor substrate opening.
- 3. (Currently Amended) A semiconductor die assembly comprising: a semiconductor substrate having a first surface and a second surface, wherein saidthe semiconductor substrate includes at least one opening defined therethrough between saidthe semiconductor substrate first surface and saidthe semiconductor substrate second surface;
- at least one semiconductor die having an active surface with at least one electrical connection area disposed on saidthe semiconductor die active surface, saidthe at least one semiconductor die oriented having saidthe at least one electrical connection area

substantially aligned with <u>saidthe</u> at least one semiconductor substrate opening, <u>said-the</u> at least one electrical connection area disposed on <u>said-the</u> semiconductor die active surface, <u>said-the</u> at least one electrical connection area directly connected to at least one output electrical connection of <u>said-the</u> semiconductor device; and

- at least one adhesive tape interposed between and attaching saidthe semiconductor die active surface and saidthe semiconductor substrate first surface, a width of saidthe at least one adhesive tape extending at least proximate an edge of saidthe at least one semiconductor die to an edge of saidthe at least one semiconductor substrate opening and extending beyond saidthe edge of saidthe at least one semiconductor die a distance on saidthe semiconductor substrate first surface to provide a detectable adhesive tape surface on saidthe semiconductor substrate first surface.
- 4. (Currently Amended) The semiconductor die assembly of claim 1, further including at least one electrical connection extending between saidthe at least one electrical connection area and at least one trace on saidthe semiconductor substrate second surface.
- 5. (Currently Amended) The semiconductor die assembly of claim 4, wherein saidthe at least one electrical connection comprises a bond wire.
- 6. (Currently Amended) The semiconductor die assembly of claim 4, wherein saidthe at least one electrical connection comprises a TAB connection.
- 7. (Currently Amended) The semiconductor die assembly of claim 4, further including a glob top material disposed within saidthe at least one semiconductor substrate opening encasing saidthe at least one electrical connection.
- 8. (Currently Amended) The semiconductor die assembly of claim 7, further including an encapsulant material encasing saidthe at least one semiconductor die and saidthe glob top material.

- 9. (Currently Amended) The semiconductor die assembly of claim 1, wherein saidthe at least one adhesive tape comprises a planar carrier film including a first surface having a first adhesive disposed thereon and a second surface having a second adhesive disposed thereon.
- 10. (Currently Amended) A semiconductor die assembly comprising:

 a semiconductor substrate having a first surface and a second surface, wherein saidthe

 semiconductor substrate includes at least one opening defined therethrough between

 saidthe semiconductor substrate first surface and saidthe semiconductor substrate second

 surface;
- at least one semiconductor die having an active surface with at least one electrical connection area disposed on saidthe semiconductor die active surface, saidthe at least one semiconductor die oriented having saidthe at least one electrical connection area substantially aligned with saidthe at least one semiconductor substrate opening; and at least one adhesive tape interposed between and attaching saidthe semiconductor die active surface and saidthe semiconductor substrate first surface, a width of saidthe at least one adhesive tape extends at least proximate an edge of saidthe at least one semiconductor die to an edge of saidthe at least one semiconductor substrate opening, saidthe at least one adhesive tape comprises a planar carrier film including a first surface having a first adhesive disposed thereon and a second surface having a second adhesive disposed thereon, and the composition of saidthe first adhesive differs from a composition of saidthe second adhesive for substantially preventing damage to a portion of the active surface of the semiconductor die by filler particles in a material used to fill the at least one opening in the substrate being located between the first surface of the substrate and the active surface of the at least one semiconductor die.

- 11. (Currently Amended) The semiconductor die assembly of claim 1, further comprising at least one fillet located proximate saidthe at least one adhesive tape and saidthe edge of saidthe at least one semiconductor die.
- 12. (Currently Amended) The semiconductor die assembly of claim 1, further comprising at least one fillet located proximate saidthe at least one adhesive tape and saidthe edge of saidthe at least one semiconductor substrate opening.
- 13. (Currently Amended) The semiconductor die assembly of claim 1, further comprising at least one fillet located proximate saidthe at least one adhesive tape and saidthe active surface of saidthe at least one semiconductor die.
- 14. (Currently Amended) The semiconductor die assembly of claim 1, further comprising at least one fillet located proximate saidthe at least one adhesive tape and saidthe semiconductor substrate first surface.
- 15. (Currently Amended) A computer comprising: at least one semiconductor die assembly, saidthe semiconductor die assembly comprising: a semiconductor substrate having a first surface and a second surface, wherein saidthe semiconductor substrate includes at least one opening defined therethrough between saidthe semiconductor substrate first surface and saidthe semiconductor substrate second surface;
- at least one semiconductor die having an active surface with at least one electrical connection area disposed on saidthe semiconductor die active surface, saidthe at least one semiconductor die oriented having saidthe at least one electrical connection area substantially aligned with saidthe at least one semiconductor substrate opening; and at least one piece of adhesive tape interposed between and attaching saidthe semiconductor die active surface and saidthe semiconductor substrate first surface, a width of one piece of adhesive tape of the two pieces of adhesive tape extending at least one of at least to said

edge of said at least one semiconductor substrate opening to provide a detectable surface within said at least one semiconductor substrate opening and at least tosaid edge of said at least one semiconductor die to provide a detectable adhesive tape surface on said semiconductor substrate first surface a width of the at least one piece of adhesive tape extending beyond at least one of an edge of the at least one semiconductor substrate opening and an edge of the at least one semiconductor die to provide a detectable surface of the at least one piece of adhesive tape.